

Customer No.: 31561
Docket No.: 11053-US-PA
Application No.: 10/707,457

Amendments To The Specification

In the Title of The Present Invention

Due to the fact that the method claims of this invention were deleted from its original application, the current title of the present invention, "METAL BONDING METHOD FOR SEMICONDUCTOR CIRCUIT COMPONENTS EMPLOYING PRESCRIBED FEEDS OF METAL BALLS," should be amended to better clarify the subject matter of the present invention. The amended title of the present invention is "Semiconductor Circuit Component with Electrodes Made from Prescribed Feeds of Metal Balls."